



**IDT Europe GmbH**

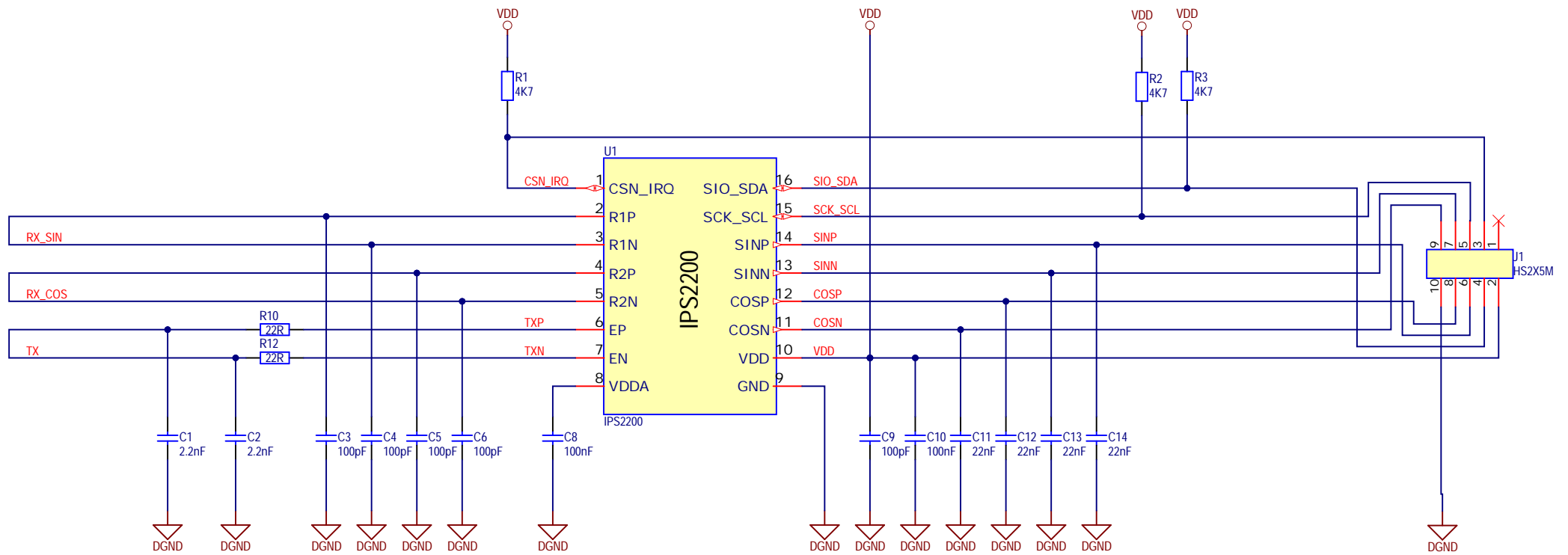
A Renesas Company


R\_59\_IPS2200\_8X45\_OD32\_ID18

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Date: 11.09.2019  
Project: R\_59\_V10\_IPS2200\_8X45\_OD32\_ID18.PrjPCB  
Version 1.0  
Content: Schematic  
Coil PCB Layout  
Coil PCB 3D Model  
Bill of Materials  
PCB Manufacture Requirements  
Coil Layer Stack  
Target PCB Layout  
Target PCB 3D Model

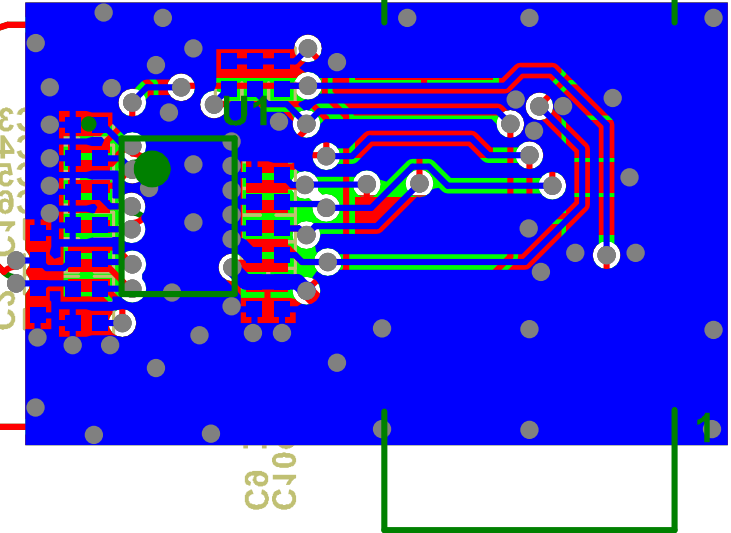
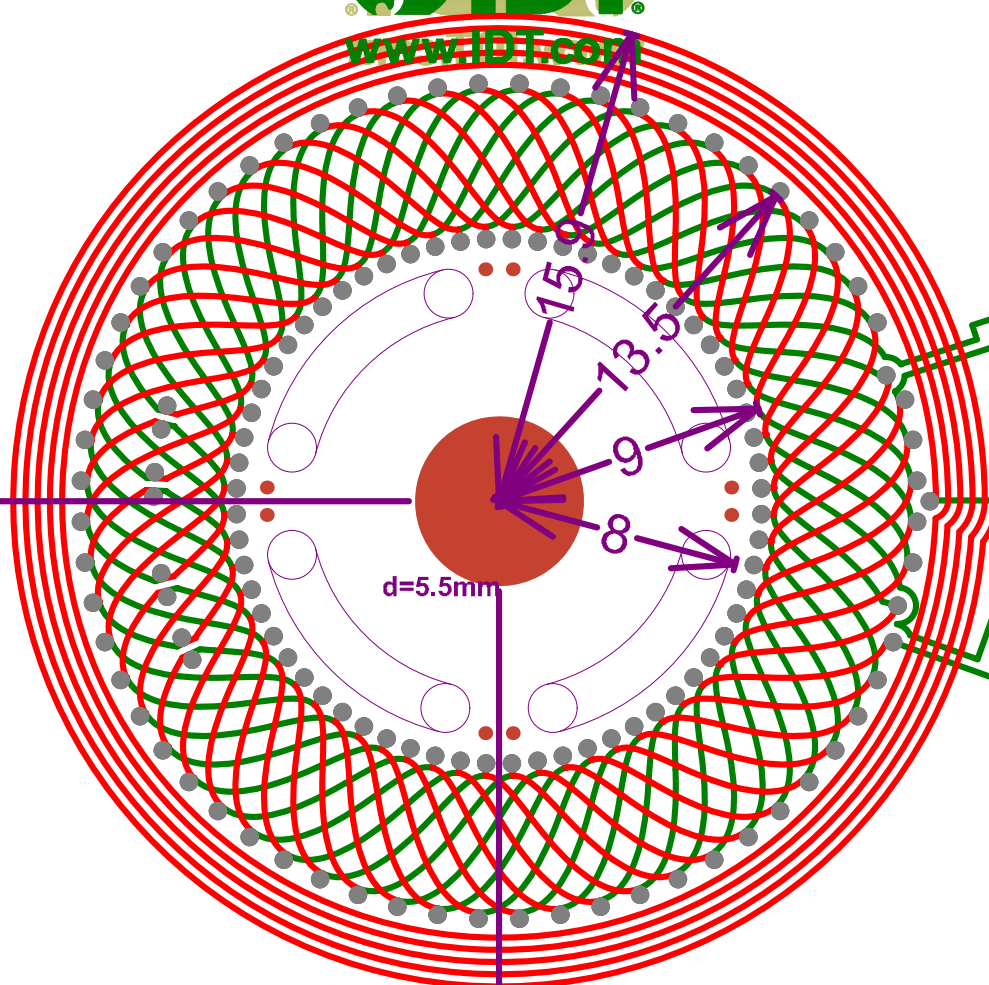
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Project name	R_59_V10_IPS2200_8X45_OD32_ID18.PrjPCB	Version	1.0	 <b>IDT</b> IDT Europe GmbH A Renesas Company
Sheet title	R_59_V10_IPS2200_8X45_OD32_ID18	Size	A4	
File name	R_59_V10_IPS2200_8X45_OD32_ID18.SCHDOC			
Date	11.09.2019	System Engineering Team	Drawn by B.GOMBOR	
Sheet		1 of 1		

ML4  
d=1.0mm

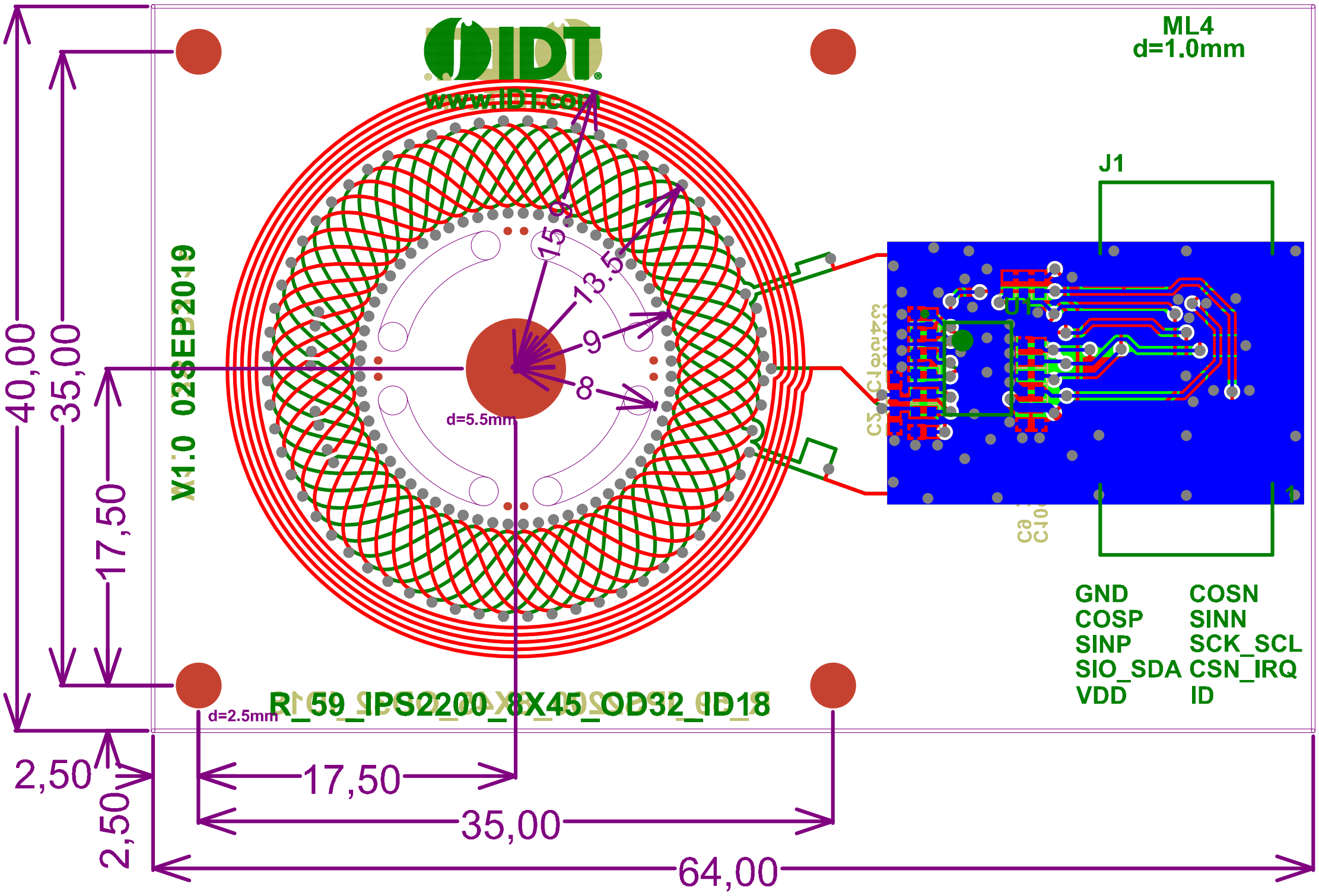
V1:0 02SEP2019



- |         |         |
|---------|---------|
| GND     | COSN    |
| COSP    | SINN    |
| SINP    | SCK_SCL |
| SIO_SDA | CSN_IRQ |
| VDD     | ID      |

R159 IPS2200 8X45 OD32 ID18

d=2.5mm





Designator	Value	Quantity	Footprint
C1, C2	2.2nF	2	C0402 3D
R1, R2, R3	4K7	3	R0402 3D
C11, C12, C13, C14	22nF	4	C0402 3D
R10, R12	22R	2	R0402 3D
C8, C10	100nF	2	C0402 3D
C3, C4, C5, C6, C9	100pF	5	C0402 3D
J1	HS2X5M	1	T821M110A1S100CEU-B
U1	IPS2200	1	TSSOP16_NVT02006














## Manufacturing requirements

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Name	R_59_V10_IPS2200_8X45_OD32_ID18
Number of layers	4
Base material	FR-4
Thickness	1.0 mm +/- 10%
Thickness of copper coating	35 µm
Final cover	ENIG
Minimal copper width	0.2 mm
Minimal copper to copper distance	0.15 mm
Via hole/pad diameter	0.3/0.6 mm
Slotted holes	no
Panel dimensions	64 x 40 mm
Silk screen color	white on both sides
Solder mask color	green

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# Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0,030mm	3,5
4		Top Layer	Copper	0,035mm	
5		Dielectric 1	FR-4	0,175mm	4,29
6		Inner Layer 1	Copper	0,035mm	
7		Dielectric 3	FR-4	0,530mm	3,96
8		Inner Layer 2	Copper	0,035mm	
9		Dielectric 2	FR-4	0,175mm	4,29
10		Bottom Layer	Copper	0,035mm	
11		Bottom Solder	Solder Resist	0,030mm	3,5
12		Bottom Overlay			
13		Bottom Paste			
	Height : 1,080mm				

